



ABSOLUTE MAXIMUM RATINGS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
COUPLER				
Total power dissipation		P_{diss}	1.2	W
Ambient temperature range		T_{amb}	-40 to +85	$^{\circ}\text{C}$
Storage temperature range		T_{stg}	-40 to +125	$^{\circ}\text{C}$
Soldering temperature ⁽¹⁾	$t \leq 10\text{ s max.}$	T_{sld}	260	$^{\circ}\text{C}$
Isolation test voltage	for 1.0 s	V_{ISO}	5300	V_{RMS}

Notes

- Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. Exposure to absolute maximum ratings for extended periods of the time can adversely affect reliability
- Refer to wave profile for soldering conditions for through hole devices
- Total power dissipation value is based on 2S2P PCB. Refer to power phototriac application note for PCB design tips

ABSOLUTE MAXIMUM RATING CURVES

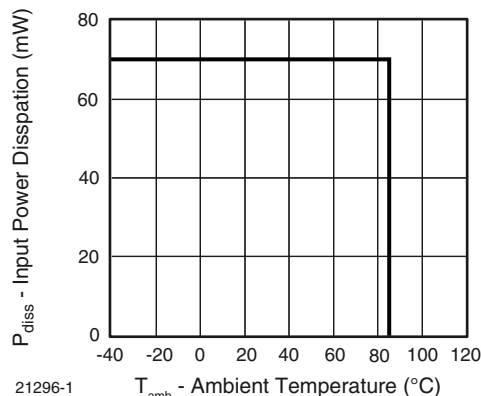


Fig. 1 - Power Dissipation vs. Temperature

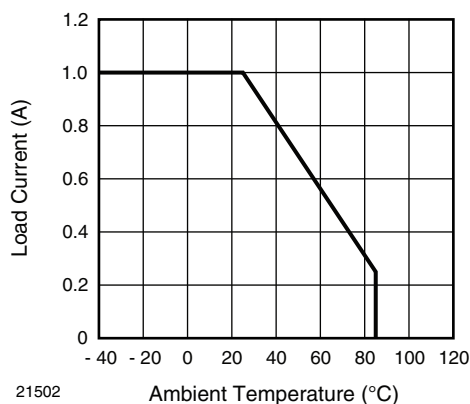


Fig. 2 - Allowable Load Current vs. Ambient Temperature

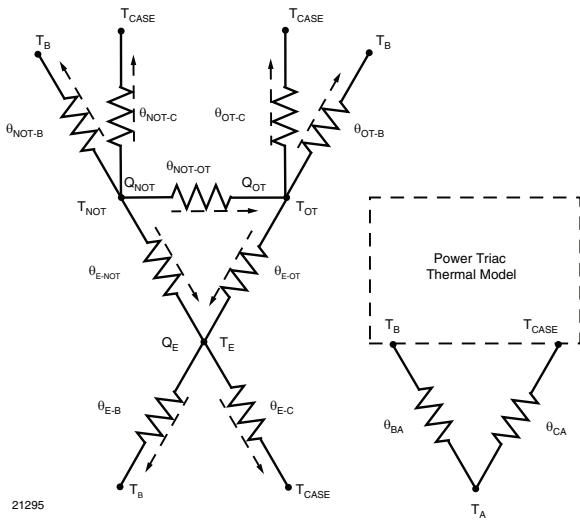
Note

- The allowable load current was calculated out under a given operating conditions and only for reference:
LED power: $Q_E = 0.015\text{ W}$, θ_{BA} (4-layer) = $30\text{ }^{\circ}\text{C/W}$

THERMAL CHARACTERISTICS			
PARAMETER	SYMBOL	VALUE	UNIT
Maximum LED junction temperature	$T_{jmax.}$	105	$^{\circ}\text{C}$
Maximum NOT junction temperature	$T_{jmax.}$	105	$^{\circ}\text{C}$
Thermal resistance, junction NOT to bord	θ_{NOT-B}	75	$^{\circ}\text{C/W}$
Thermal resistance, junction NOT to case	θ_{NOT-C}	150	$^{\circ}\text{C/W}$
Thermal resistance, junction OT to board	θ_{OT-B}	158	$^{\circ}\text{C/W}$
Thermal resistance, junction OT to case	θ_{OT-C}	157	$^{\circ}\text{C/W}$
Thermal resistance, junction emitter to board	θ_{E-B}	149	$^{\circ}\text{C/W}$
Thermal resistance, junction emitter to case	θ_{E-C}	161	$^{\circ}\text{C/W}$
Thermal resistance, junction NOT to junction OT	θ_{NOT-OT}	243	$^{\circ}\text{C/W}$
Thermal resistance, junction emitter to junction NOT	θ_{E-NOT}	420	$^{\circ}\text{C/W}$
Thermal resistance, junction emitter to junction OT	θ_{E-OT}	235	$^{\circ}\text{C/W}$
Thermal resistance, case to ambient	θ_{CA}	130	$^{\circ}\text{C/W}$

Note

- The thermal model is represented in the thermal network below. Each resistance value given in this model can be used to calculate the temperatures at each node for a given operating condition. The thermal resistance from board to ambient will be dependent on the type of PCB, layout and thickness of copper traces. For a detailed explanation of the thermal model, please reference Vishay's Thermal Characteristics of Power Phototriac application note



- NOT: Non-opto-triac
- OT: Opto-triac
- T_B: Board temperature
- T_{CASE}: Case temperature
- T_A: Ambient temperature
- θ_{BA}: Thermal resistance, board to ambient
- Q_E: LED power dissipation
- Q_{OT}: OT power dissipation
- Q_{NOT}: NOT power dissipation

Thermal Model

ELECTRICAL CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
INPUT						
LED trigger current	V _T = 6 V	I _{FT}	-	-	10	mA
Input reverse current	V _R = 5 V	I _R	-	-	10	μA
LED forward voltage	I _F = 10 mA	V _F	0.9	-	1.4	V
OUTPUT						
Peak on-state voltage	I _{TM} = 1.5 A	V _{TM}	-	-	1.7	V
Repetitive peak off-state current	V _{DRM} = 600 V, T _A = 110 °C, 60 Hz	I _{DRM}	-	-	100	μA
Holding current	R _L = 100 Ω	I _H	-	-	25	mA
Critical rate of rise of off-state voltage	V _{IN} = 400 V (Fig. 3)	dV/dt _{cr}	-	210	-	V/μs
Critical rate of rise of commutating voltage	V _{IN} = 240 V _{RMS} , I _T = 1 A _{RMS} (Fig. 3)	dV/dt _{crq}	-	0.9	-	V/μs

Note

- Minimum and maximum values are testing requirements. Typical values are characteristics of the device and are the result of engineering evaluations. Typical values are for information only and are not part of the testing requirements

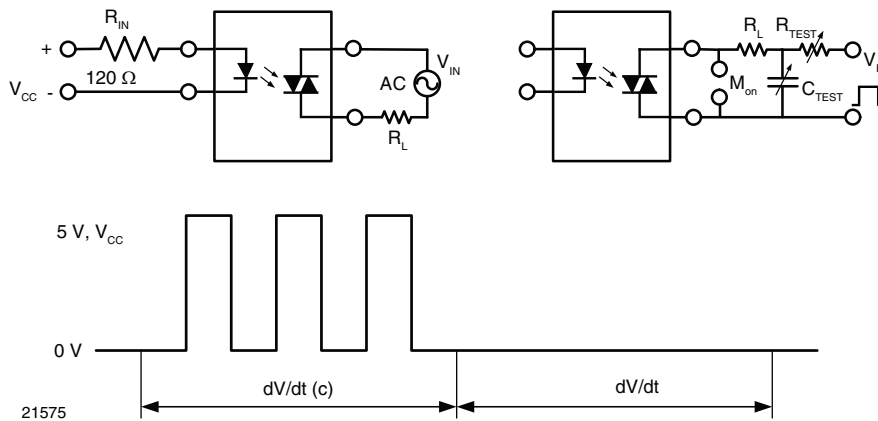


Fig. 3 - dV/dt Test Circuit



RECOMMENDED OPERATING CONDITIONS							
PARAMETER		TEST CONDITION	SYMBOL	MIN.	MAX.	UNIT	
Forward current at on-state		Input	$I_{F(ON)}$	10	20	mA	
Forward current at off-state			$I_{F(OFF)}$	0	0.1	mA	
Load supply voltage		Output	With snubber (0.022 μ F, 47 Ω)	$V_{OUT(RMS)}$	-	240	V
On-state RMS current	$T_A = 40\text{ }^\circ\text{C}$		On 4-layer PCB ($R_{BA} = 30\text{ }^\circ\text{C/W}$)	$I_{OUT(RMS)}$	-	0.8	A
	$T_A = 60\text{ }^\circ\text{C}$			$I_{OUT(RMS)}$	-	0.6	A
Frequency			f	50	60	Hz	
Operating temperature				- 40	85	$^\circ\text{C}$	

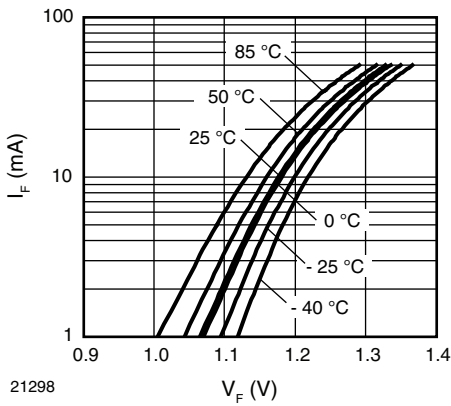
SAFETY AND INSULATION RATINGS							
PARAMETER		TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Climatic classification		IEC 68 part 1		-	40 / 85 / 21	-	
Pollution degree		DIN VDE 0109		-	2	-	
Tracking resistance (comparative tracking index)		Insulation group IIIa	CTI	175	-	-	
Highest allowable overvoltage		Transient overvoltage	V_{IOTM}	8000	-	-	V_{peak}
Maximum working insulation voltage		Recurring peak voltage	V_{IORM}	890	-	-	V_{peak}
Insulation resistance at 25 $^\circ\text{C}$		$V_{IO} = 500\text{ V}$	R_{IS}	-	-	$\geq 10^{12}$	Ω
Insulation resistance at T_S		$V_{IO} = 500\text{ V}$	R_{IS}	-	-	$\geq 10^9$	Ω
Insulation resistance at 100 $^\circ\text{C}$		$V_{IO} = 500\text{ V}$	R_{IS}	-	-	$\geq 10^{11}$	Ω
Partial discharge test voltage		Method b, $V_{pd} = V_{IORM} \times 1.6$	V_{pd}	-	-	1424	V_{peak}
Safety limiting values - maximum values allowed in the event of a failure	Output power		P_{SO}	-	-	2	W
	Input current		I_{SI}	-	-	150	mA
	Case temperature		T_{SI}	-	-	165	$^\circ\text{C}$
Minimum external air gap (clearance)		Measured from input terminals to output terminals, shortest distance through air		≥ 7	-	-	mm
Minimum external tracking (creepage)		Measured from input terminals to output terminals, shortest distance path along body		≥ 7	-	-	mm

Note

- This phototriac coupler is suitable for 'safe electrical insulation' only within the safety ratings. Compliance with safety ratings shall be ensured by means of protective circuits

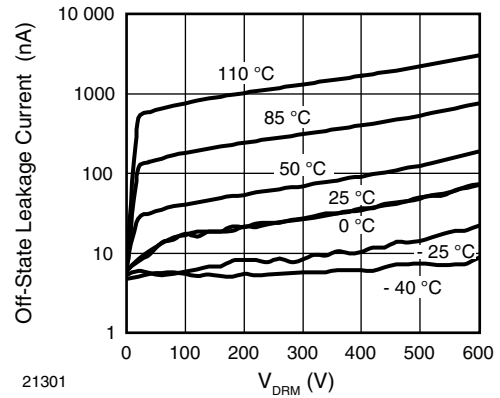


TYPICAL CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)



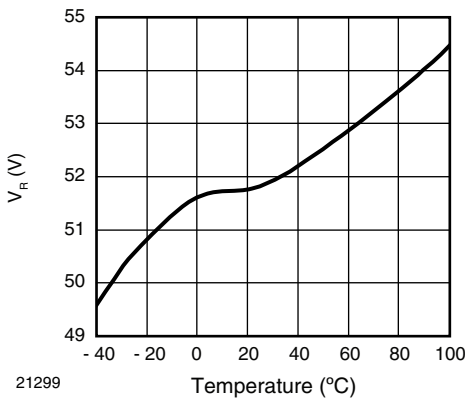
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Fig. 4 - Forward Current vs. Forward Voltage



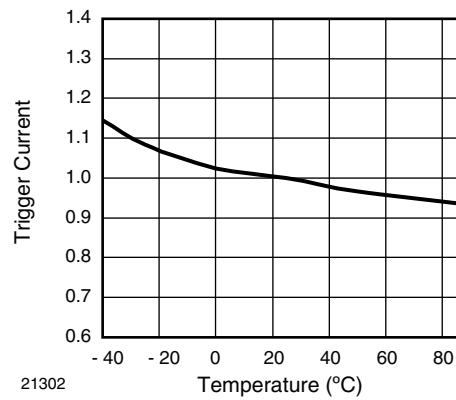
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Fig. 7 - Off-State Leakage Current vs. Voltage



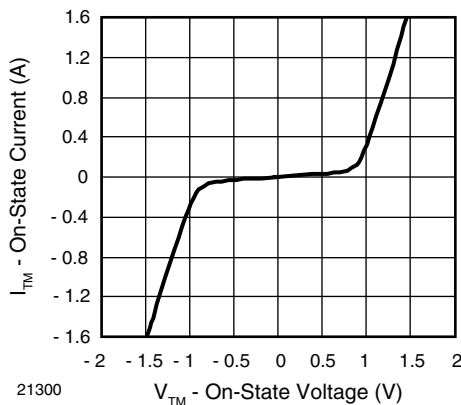
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Fig. 5 - Diode Reverse Voltage vs. Temperature



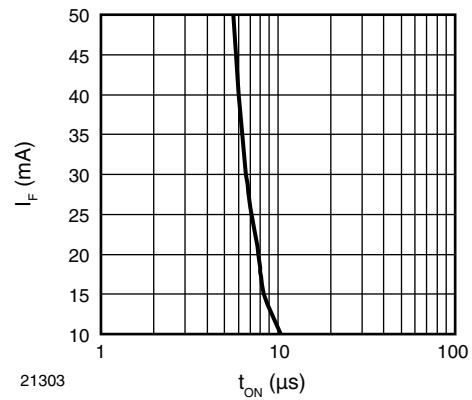
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Fig. 8 - Normalized Trigger Input Current vs. Temperature



21300

Fig. 6 - On-State Current vs. On State Voltage



21303

Fig. 9 - Trigger Input Current vs. Turn-on Time

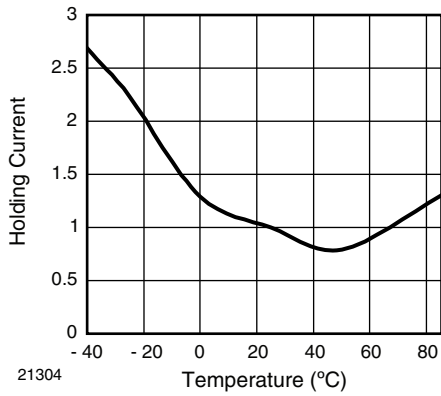


Fig. 10 - Normalized Holding Current vs. Temperature

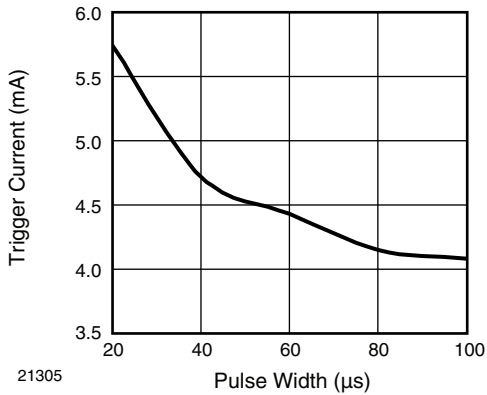


Fig. 11 - Trigger Current vs. Trigger Pulse Width

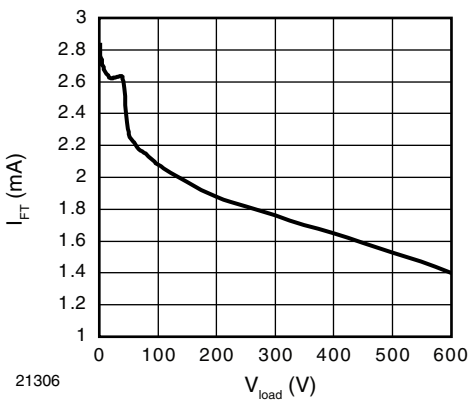
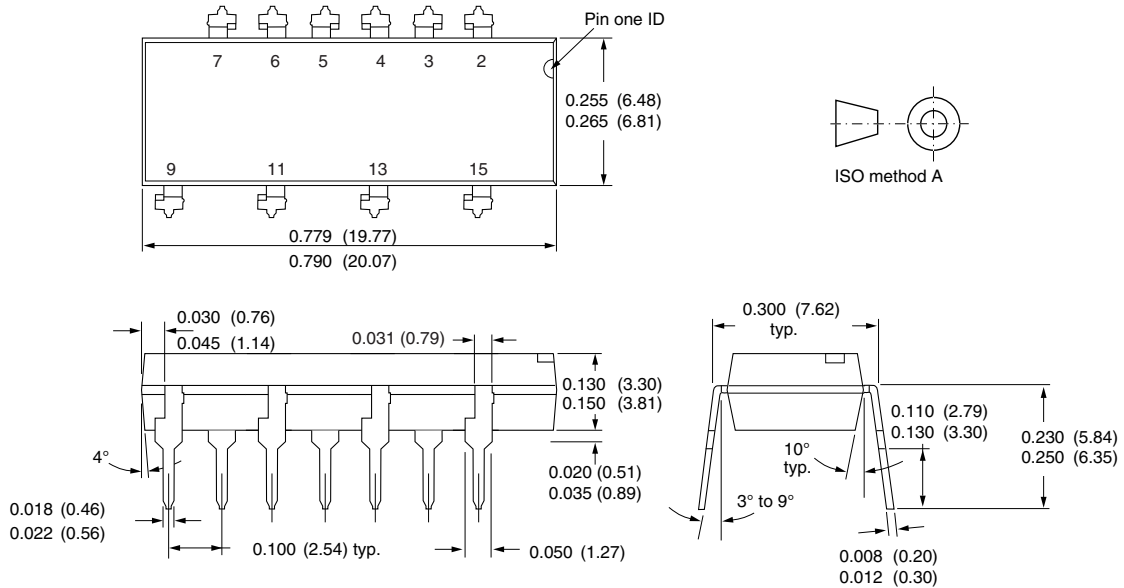


Fig. 12 - Trigger Current vs. V_{load}

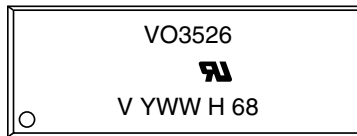


PACKAGE DIMENSIONS in inches (millimeters)



21083

PACKAGE MARKING





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